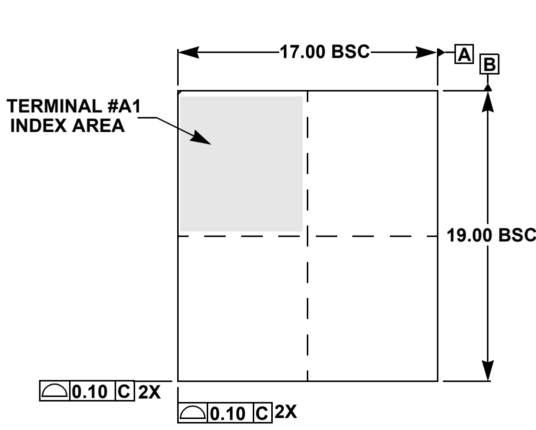
Package Outline Drawing

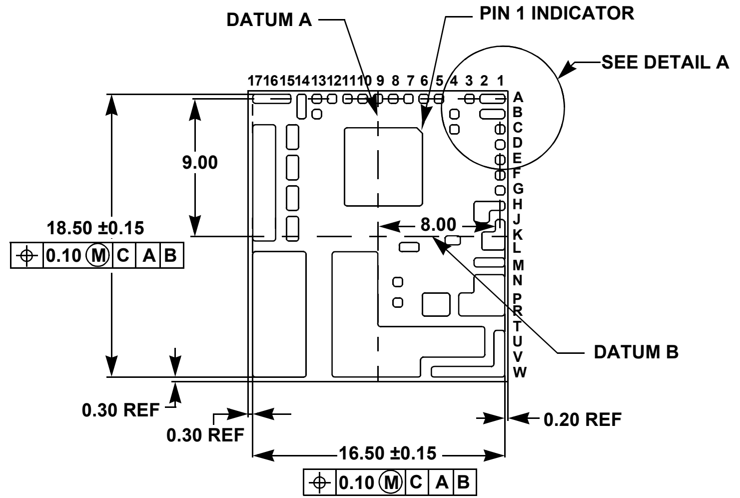
Y40.17x19

40 I/O 17.0mm x 19.0mm x 3.55mm HDA MODULE

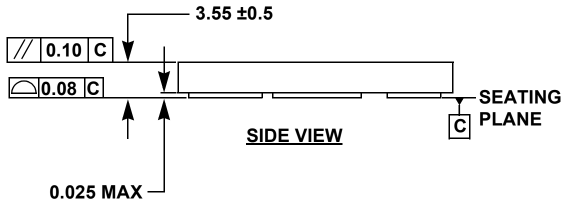
Rev 3, 4/17



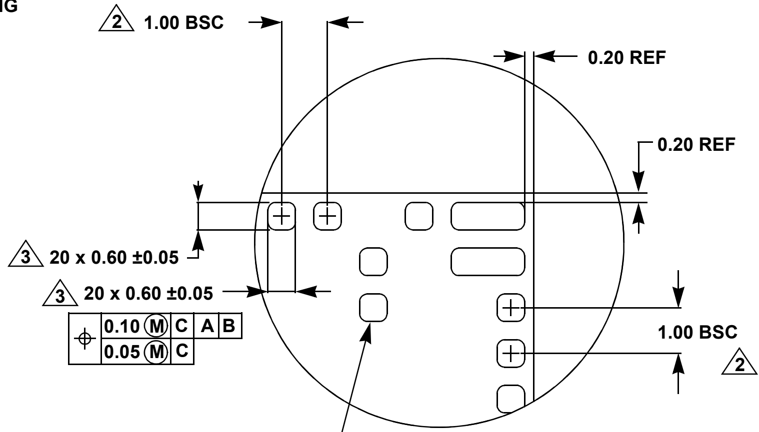
TOP VIEW



BOTTOM VIEW



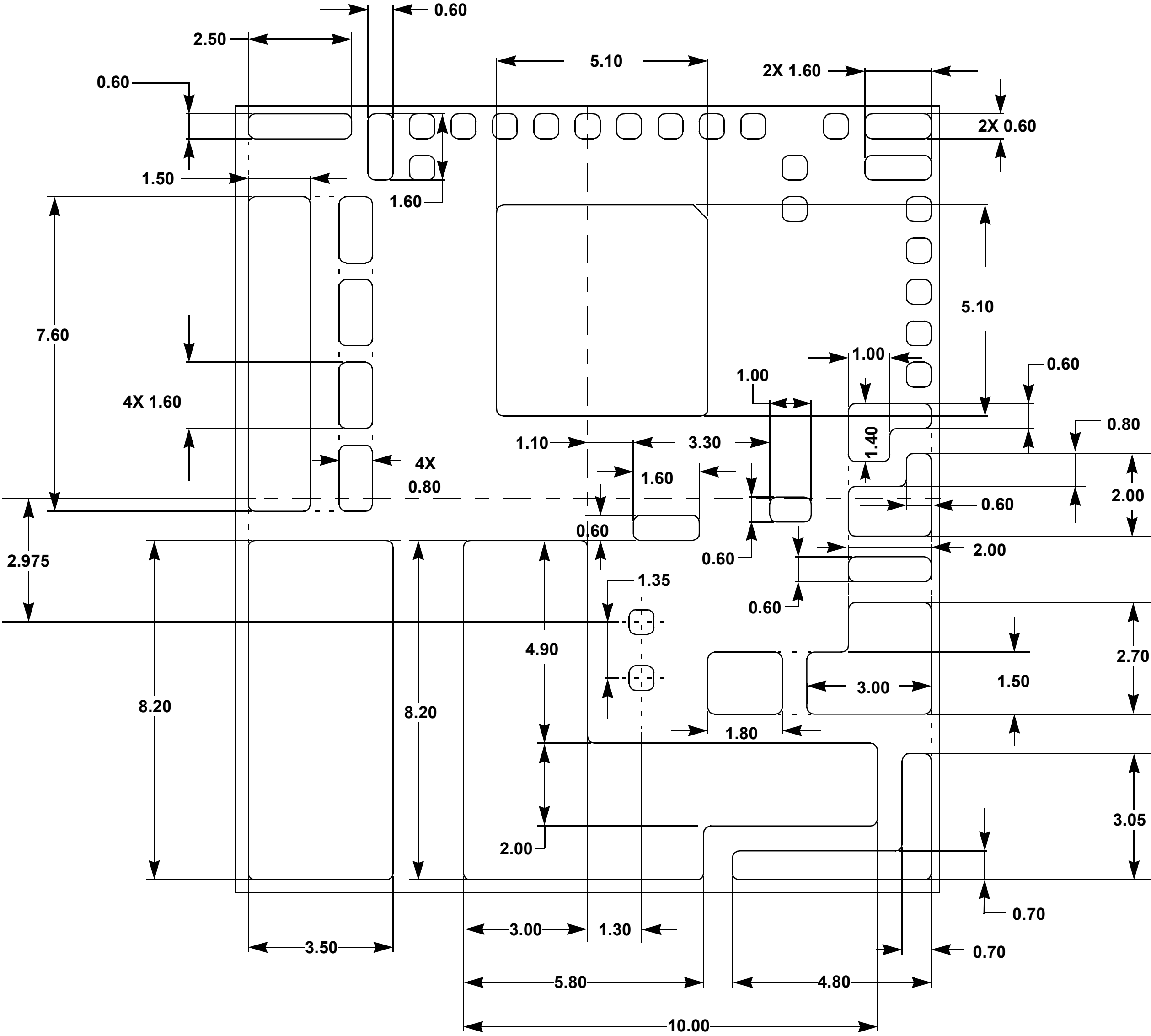
SIDE VIEW



DETAIL A

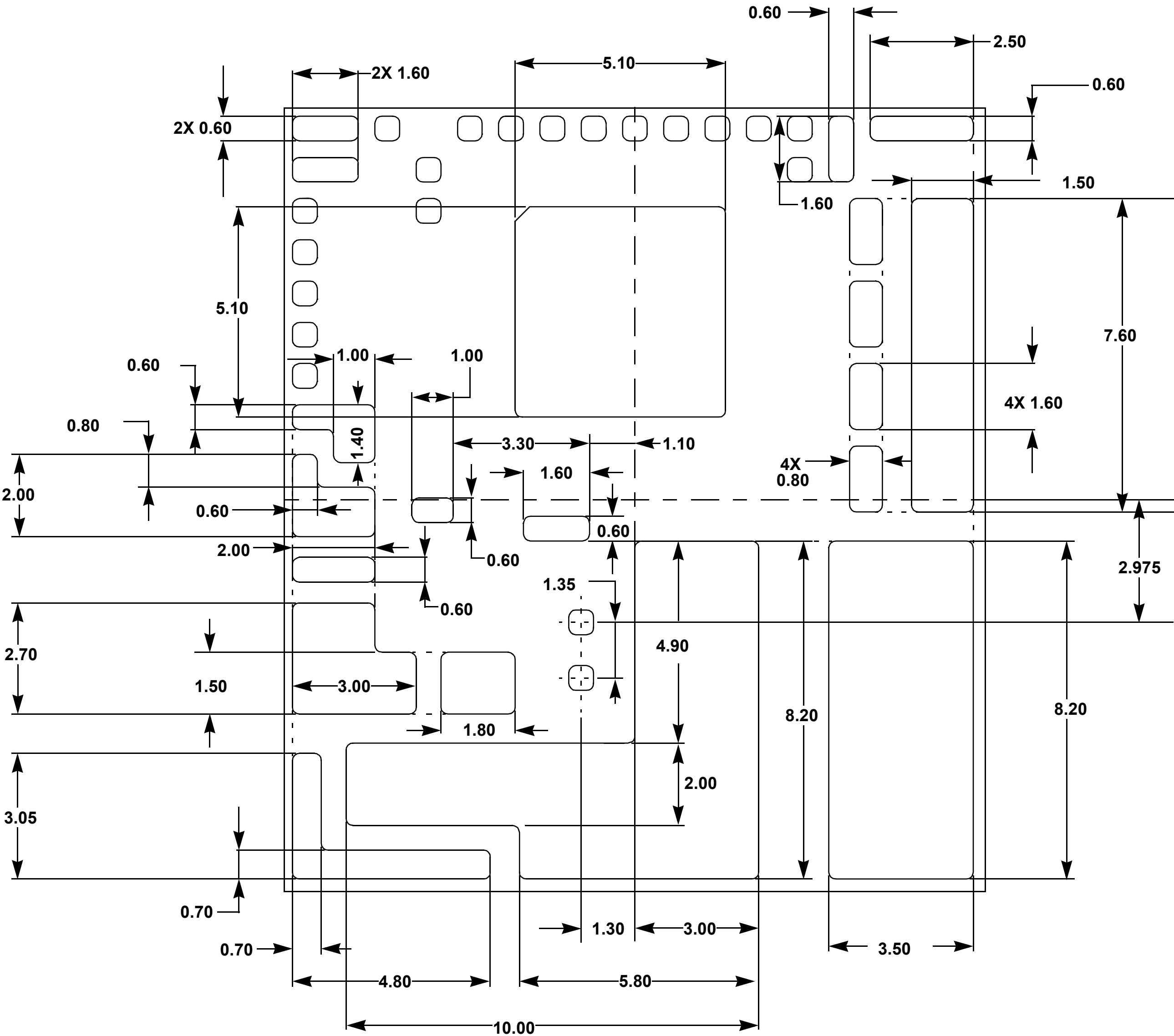
NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. (2) REPRESENTS THE BASIC LAND GRID PITCH.
3. (3) THE TOTAL NUMBER OF I/O (EXCLUDING DUMMY PADS)
4. UNLESS OTHERWISE SPECIFIED, TOLERANCE: DECIMAL ±0.10
5. DIMENSIONING AND TOLERANCING PER ASME Y14.M-2009
6. THE CONFIGURATION OF THE PIN#1 IDENTIFIER IS OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARK FEATURE.



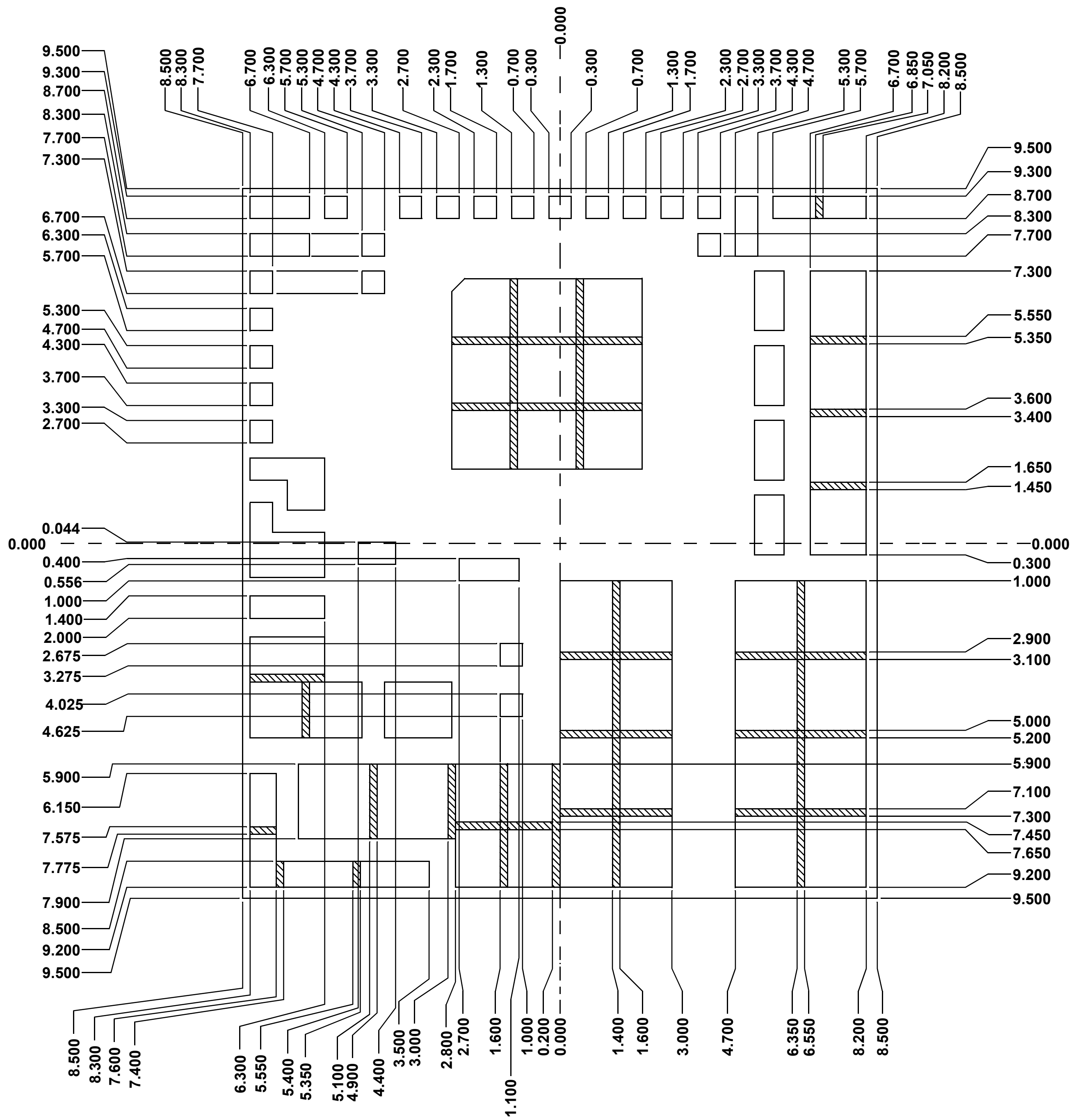
SIZE DETAILS FOR THE 16 EXPOSED DAPS

BOTTOM VIEW



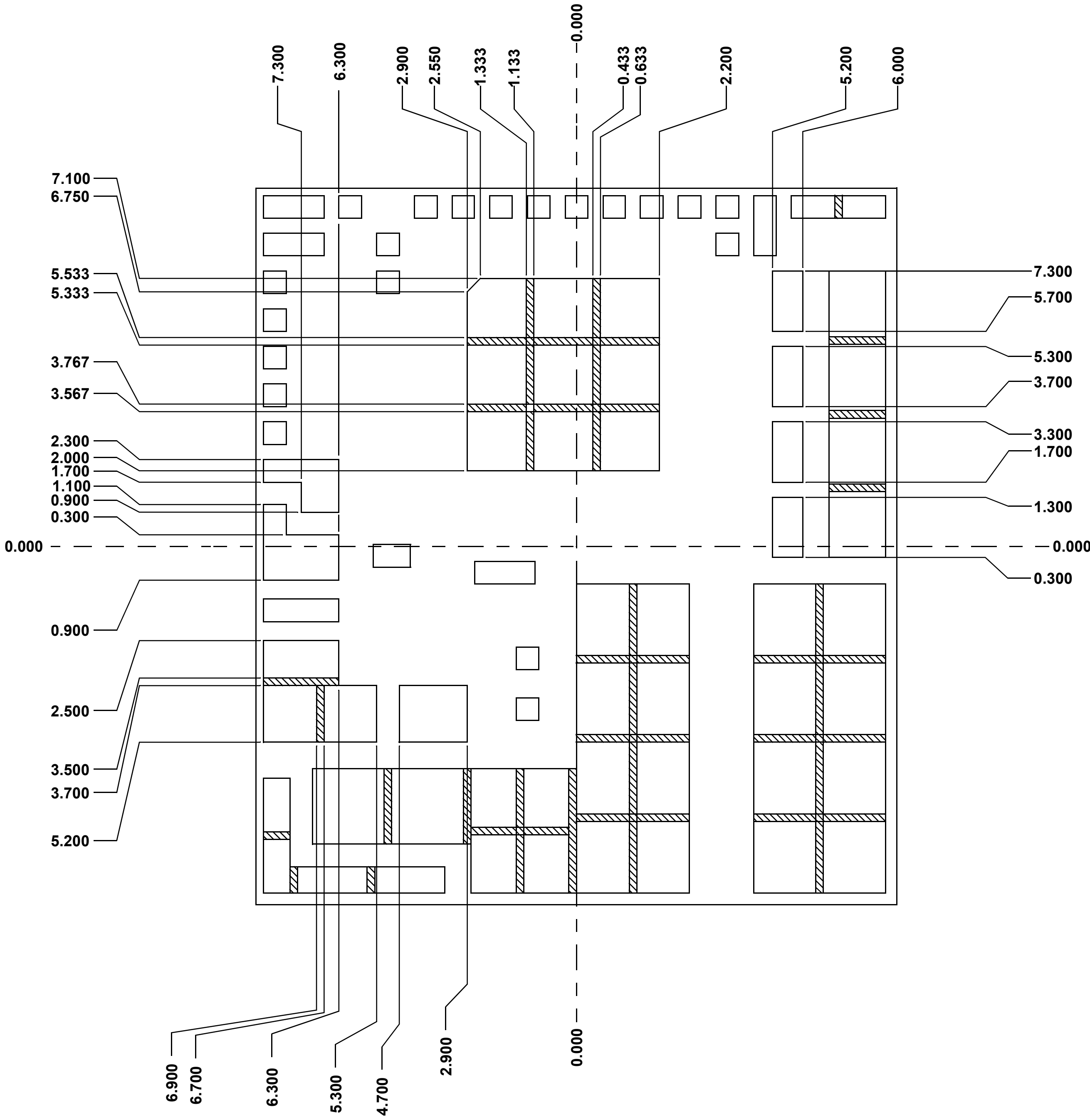
SIZE DETAILS FOR THE 16 EXPOSED DAPS

TOP VIEW



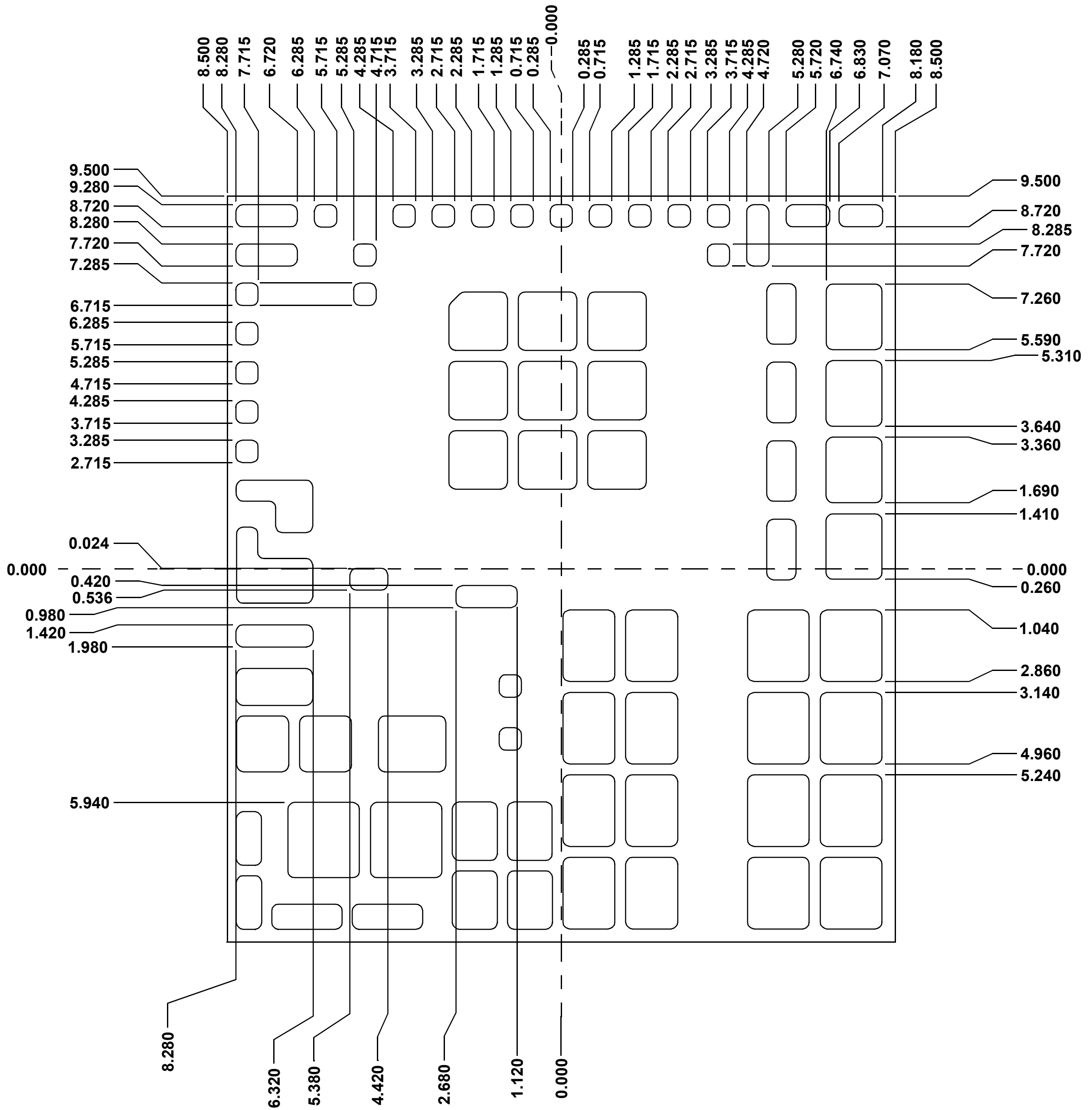
RECOMMENDED SOLDER MASK DEFINED PCB LAND PATTERN (SHEET 1 OF 2)

TOP VIEW



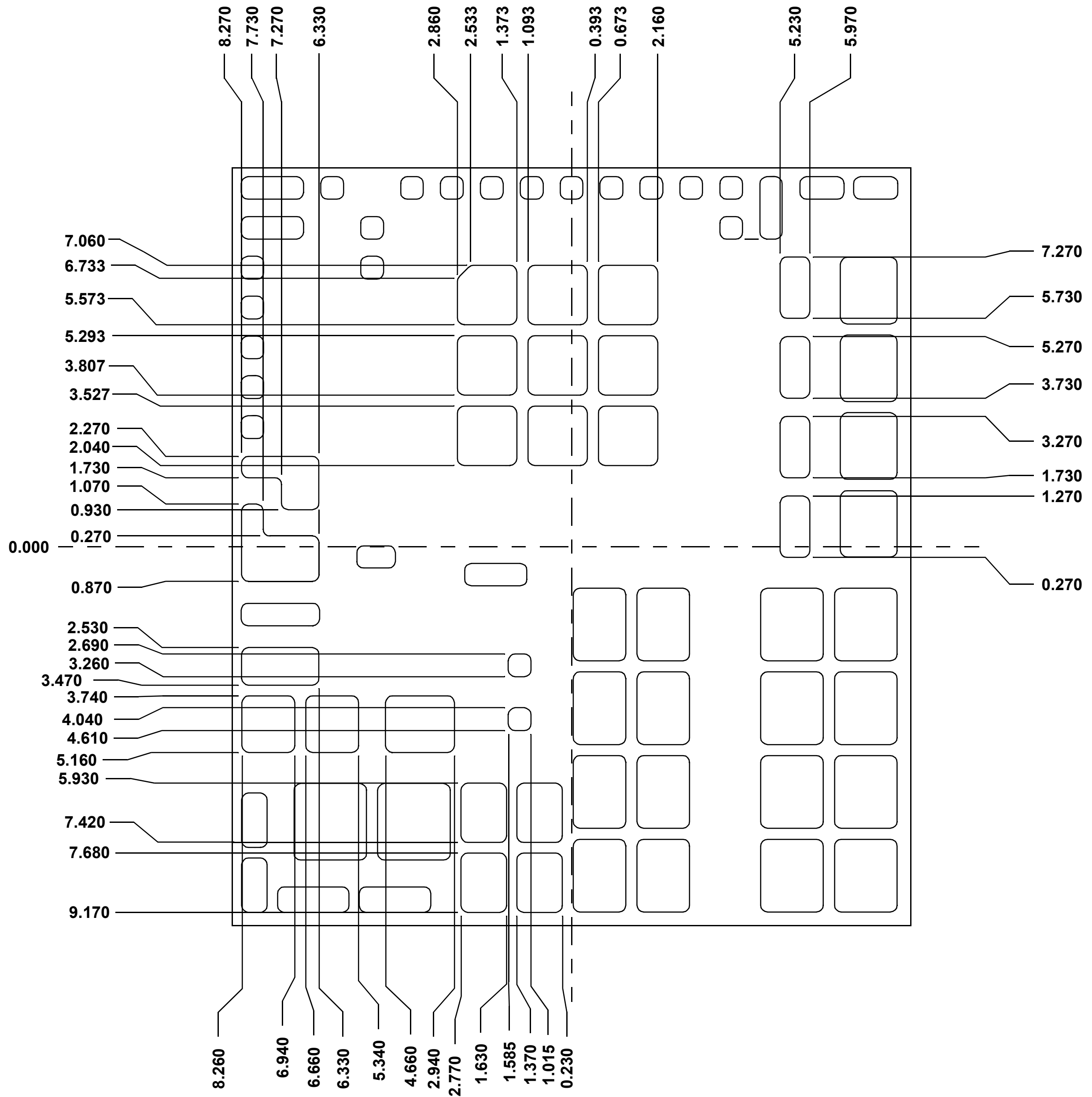
RECOMMENDED SOLDER MASK DEFINED PCB LAND PATTERN (SHEET 2 OF 2)

TOP VIEW



RECOMMENDED STENCIL PATTERN (90% PASTE TO PAD) (SHEET 1 OF 2)

TOP VIEW



RECOMMENDED STENCIL PATTERN (90% PASTE TO PAD) (SHEET 2 OF 2)

TOP VIEW